



Material Content Data Sheet



Sales Product Name	BFR 843EL3 E6327			Issued	24. January 2018			
MA#	MA001642152							
Package	PG-TSLP-3-10			Weight*	0.47 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.01		84	
	noble metal	gold	7440-57-5	0.004	0.84		8382	
	inorganic material	silicon	7440-21-3	0.024	5.16	6.01	51641	60107
leadframe	non noble metal	nickel	7440-02-0	0.073	15.63	15.63	156326	156326
wire	noble metal	gold	7440-57-5	0.009	1.94	1.94	19351	19351
encapsulation	organic material	carbon black	1333-86-4	0.002	0.36		3560	
	plastics	epoxy resin	-	0.048	10.32		103250	
	inorganic material	silicondioxide	60676-86-0	0.281	60.52	71.20	605262	712072
leadfinish	noble metal	gold	7440-57-5	0.010	2.26	2.26	22563	22563
plating	noble metal	palladium	7440-05-3	0.003	0.70		7018	
	noble metal	gold	7440-57-5	0.010	2.26	2.96	22563	29581
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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